

**IN THE CLAIMS:**

Claims 1, 2 and 15-20 have been amended herein. Please note that all claims currently pending and under consideration in the referenced application are shown below. Please enter these claims as amended. This listing of claims will replace all prior versions and listings of claims in the application.

**Listing of Claims:**

1. (Currently Amended) A method for forming an interposer substrate, comprising: providing a rectangular, substantially planar substrate comprising a dielectric ~~material~~material and having a longitudinal axis;  
forming a first elongated interconnect slot having a longitudinal axis and at least a second elongated interconnect slot having a longitudinal axis, ~~a longitudinal axis of the first interconnect slot and the at least a second interconnect slot~~including:  
positioning the longitudinal axis of each of the first elongated interconnect slot and the at least a second elongated interconnect slot to slot positioned approximately collinear to a the longitudinal centerline of the substrate;  
longitudinally separating the first elongated interconnect slot from the at least a second elongated interconnect slot separated by forming at least one transversely extending crosspiece from the at least a second interconnect slot; and  
sizing, configuring and positioning the first elongated interconnect slot and the at least a second elongated interconnect slot being sized and configured for respective alignment with a first plurality of bond pads and at least a second plurality of bond pads on a single semiconductor die when the semiconductor die is to be placed on the substantially planar substrate, to enable respective access to the first plurality of bond pads and the at least a second plurality of bond pads being accessible through the first elongated interconnect slot and the at least a second elongated interconnect slot.

2. (Currently Amended) The method of claim 1, further comprising forming the first elongated interconnect slot and the at least a second elongated interconnect slot by milling through the substrate and forming the at least one transversely extending crosspiece ~~comprises~~ comprising leaving at least one unmilled portion of the substrate lying intermediate opposing, distal ends of the first elongated interconnect slot and the at least a second elongated interconnect slot.

3. (Previously presented) The method of claim 2, further comprising producing filleted side edges on the at least one transversely extending crosspiece during the milling.

4. (Withdrawn) The method of claim 1, wherein forming the first elongated interconnect slot and the at least a second elongated interconnect slot comprises forming a unitary elongated interconnect slot and forming the at least one transversely extending crosspiece by bonding a segment of material transversely across the unitary interconnect slot at a location intermediate opposing ends thereof.

5. (Withdrawn) The method of claim 4, wherein forming the at least one transversely extending crosspiece comprises forming a tape segment coated with an adhesive on opposing sides thereof and adhering the tape segment to a surface of the substantially planar substrate.

6. (Withdrawn) The method of claim 1, wherein forming the first elongated interconnect slot and the at least a second elongated interconnect slot comprises forming a unitary elongated interconnect slot, forming an "I"-shaped segment of material and bonding a head portion of the "I"-shaped segment to the substrate on one side of the unitary interconnect slot and a foot portion of the "I"-shaped segment to the substrate on an opposing side of the unitary interconnect slot with a body portion of the "I"-shaped segment extending transversely thereacross to form the at least one transversely extending crosspiece.

7. (Withdrawn) The method of claim 6, further comprising forming the “I”-shaped segment as a film having an adhesive coating on opposing sides thereof.

8. (Withdrawn) The method of claim 6, further comprising forming the “I”-shaped segment as a substantially rigid plastic segment.

9. (Withdrawn) The method of claim 1, wherein forming the first elongated interconnect slot and the at least a second elongated interconnect slot comprises forming a unitary elongated interconnect slot, forming a “T”-shaped element having a body and a cap, extending the body into the unitary interconnect slot in contact with opposing sides thereof and bonding legs of the cap extending transversely to the unitary interconnect slot over a surface of the substrate thereto to form the at least one transversely extending crosspiece.

10. (Withdrawn) The method of claim 1, wherein forming the first elongated interconnect slot and the at least a second elongated interconnect slot comprises forming a unitary elongated interconnect slot, forming a tape segment of a polymeric material containing a reinforcement material, disposing the tape segment transversely across the unitary interconnect slot and bonding the tape segment to a surface of the substrate.

11. (Withdrawn) The method of claim 1, wherein forming the first elongated interconnect slot and the at least a second elongated interconnect slot comprises forming a unitary elongated interconnect slot, interposing a bar of material transversely between opposing sides of the unitary interconnect slot and bonding the bar thereto.

12. (Previously presented) The method of claim 1, further comprising forming the first elongated interconnect slot and the at least a second elongated interconnect slot to a combined length of about 67% or more of a length of the substrate.

13. (Previously presented) The method of claim 12, further comprising forming the first elongated interconnect slot and the at least a second elongated interconnect slot to a combined length of about 70 to 80% of a length of the substrate.

14. (Previously presented) The method of claim 1, further comprising locating the at least one transversely extending crosspiece substantially at a longitudinal midpoint of a combined length of the first elongated interconnect slot and the at least a second elongated interconnect slot.

15. (Currently Amended) A method for forming an interposer substrate, comprising: providing a rectangular, substantially planar substrate comprising a dielectric material and having a longitudinal centerline;

~~forming-positioning and forming at least a plurality of elongated interconnect slots, with a~~

longitudinal axis of each of the ~~at least a plurality of~~ elongated interconnect slots positioned approximately collinear to ~~a the~~ longitudinal centerline of the substrate;

;

separating each of the at least a plurality of elongated interconnect slots separated from at least one other elongated interconnect slot of the plurality by forming at least one of a plurality of transversely extending crosspieces from at least another of the at least a plurality of interconnect slots;

sizing, configuring and positioning each of the at least a plurality of elongated

~~interconnect slots being sized and configured for respective alignment with a first plurality and at least a second plurality of bond pads on a single semiconductor die when the semiconductor die is to be placed on the substantially planar substrate, to enable access to each plurality the of bond pads being accessible through the at least one elongated interconnect slot of the plurality plurality of interconnect slots;~~

16. (Withdrawn-Currently Amended) The method of claim 15, further comprising forming the ~~at least a plurality of~~ elongated interconnect slots by milling approximately the same

distance through the substrate to form each of the at least a plurality of elongated interconnect slots and forming the ~~at least a plurality of transversely extending crosspieces~~ comprise by leaving at least a plurality of unmilled portions of the substrate.

17. (Withdrawn-Currently Amended) The method of claim 16, further comprising producing filleted side edges on the ~~at least a plurality of transversely extending crosspieces~~ during the milling.

18. (Withdrawn-Currently Amended) The method of claim 15, further comprising forming the ~~at least a plurality of elongated interconnect slots~~ to a combined length of about 67% or more of a length of the substrate.

19. (Withdrawn-Currently Amended) The method of claim 18, further comprising forming the ~~at least a plurality of elongated interconnect slots~~ to a combined length of about 70 to 80% of a length of the substrate.

20. (Withdrawn-Currently Amended) The method of claim 15, further comprising locating each of the ~~at least a plurality of transversely extending crosspieces~~ approximately equidistant from at least a first longitudinally adjacent crosspiece and one of a second longitudinally adjacent crosspiece and an end of an elongated interconnect slot.